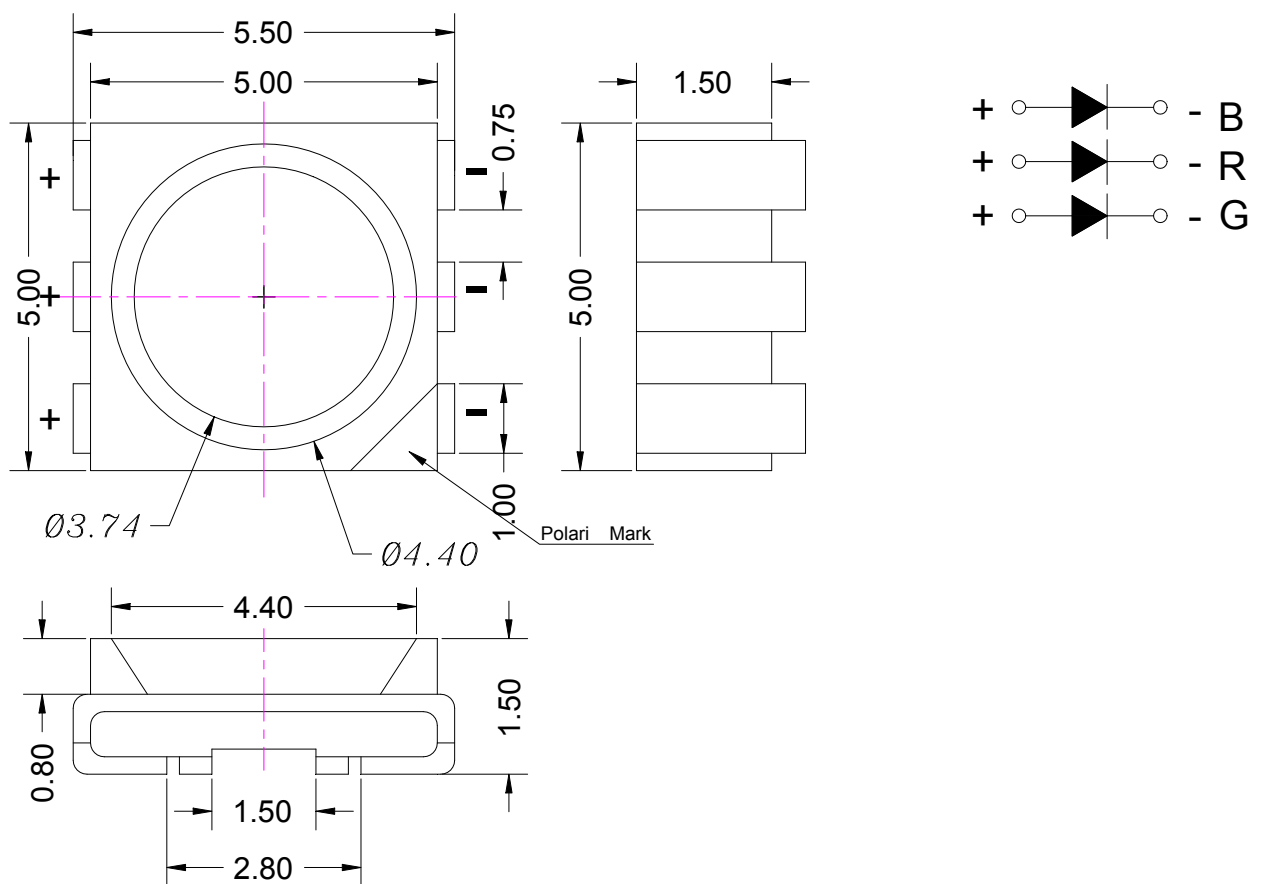




Wen Li	Fang Yang	Jiang Yang	Fang Wang



Tolerance: 0.25(0.01)



Unit mm

Color RGB

Length -color Water clear

Emitting Material InGaN

Drawing byoliaion



3 Characteristic

Forward current	If	30	mA			
Reverse voltage	Vr	5	V			
Power dissipation	Pd	110	mW			
Operating temperature range	Top	-25 +80	C			
Storage temperature range	T g	-30 +80	C			
Peak pulsed current 1/8 d f=1KH	Ifp	125	mA			
Wavelength peak emission (R)	If=20mA	peak	620	625	630	nm
Wavelength peak emission (G)			515	520	525	
Wavelength peak emission (B)			460	465	470	
Spectral half bandwidth	If=20mA			10		
Forward voltage (R)	If=20mA	Vf	1.8	2.0	2.4	V
Forward voltage (G)			3.0	3.3	3.6	
Forward voltage (B)			3.0	3.3	3.6	
Luminous intensity (R)	If=20mA	I	800	1000	1200	mcd
Luminous intensity (G)			3000	3500	4000	
Luminous intensity (B)			400	500	600	
Viewing angle at 50% IV	If=10mA		--	120	--	Deg
Reverse current	Vr=5V	Ir	--	--	5	A



Useful life

-

IF=20mA

100000

H

Typical Electrical/Optical Characteristic Curve
(Ta=25 Unless Otherwise Noted)

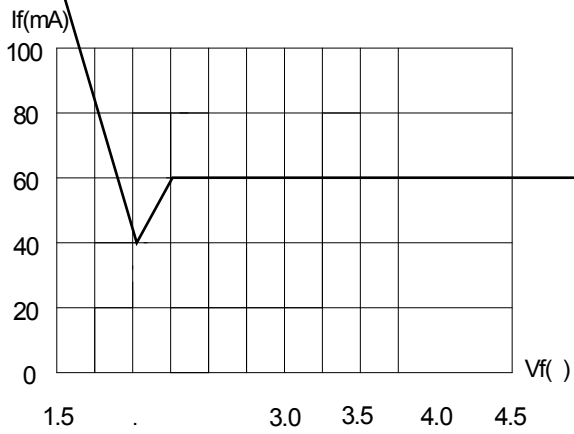


Fig.1 Forward Current vs Forward Voltage

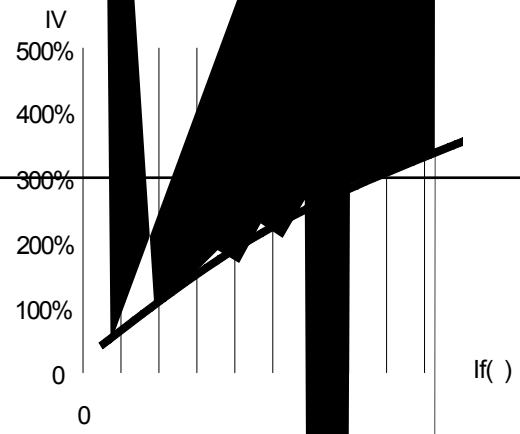


Fig.2 Relative Luminous Intensity vs Forward Current



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sucp

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ms-aw

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i Iron Soldering: The Iron (max 30W) end temperature less than 300 °C, soldering time 3 seconds, soldering position is minimum 2mm from board.

ii Dip Soldering: Max temperature is 260 °C, time 5s, the position is minimum 2mm from board.

i Bracket must be bent only 2mm from colloid.

ii Bracket mold must be finished before or professional.

iii Bracket mold must be finished before soldering.

i Bracket mold hold a wire the connection between the pin, the distance gap of lead and the circuit board.

i. I should pay attention to the soldering of the device in case of wrong position. The device can be damaged by the

temperature, working conditions can be affected by the

ii. I should pay attention to the LED the lead wire deformation

in the assembly in order to accurately locate the position of the lead wire and the distance of the lead wire

i. Soldering of the lead wire positioning

.

